

AMENDMENTS TO THE CLAIMS

Please replace the claims, including all prior versions, with the listing of claims found below.

Listing of Claims:

1-71. (Canceled)

72. (Withdrawn) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element; and

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector, wherein the sealing resin contains the fluorescent substance.

73. (Withdrawn) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

a layer of the fluorescent substance provided on a outside surface of the sealing resin.

74. (Withdrawn) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector;

a layer of the fluorescent substance provided on a reflective surface of the reflector; and

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device.

75. (Withdrawn) The semiconductor light-emitting device according to Claim 65, further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

a layer of the fluorescent substance provided on a reflective surface of the reflector, wherein the base substance is a substrate provided with a recessed portion, and at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion of the substrate so as not to emit light from the semiconductor light-emitting element directly to an outside of the semiconductor light-emitting device.

76. (Withdrawn) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element; and

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector, wherein the sealing resin contains the fluorescent substance.

77. (Withdrawn) A semiconductor light-emitting device constituted by mounting a semiconductor

light-emitting element on a base substance, wherein the semiconductor light-emitting element has

outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

a layer of the fluorescent substance provided on a outside surface of the sealing resin.

78. (Withdrawn) A semiconductor light-emitting device constituted by mounting a semiconductor

light-emitting element on a base substance, wherein the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector;

a layer of the fluorescent substance provided on a reflective surface of the reflector; and

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device.

79. (Withdrawn) A semiconductor light-emitting device constituted by mounting a semiconductor light-emitting element on a base substance, wherein the semiconductor light-emitting

element has outgoing light having emission wavelengths of 390 to 420 nm;

a first fluorescent substance, a second fluorescent substance and a third fluorescent substance are included;

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm;

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color;

the semiconductor light-emitting device further comprising:

a reflector having a cross section substantially in a quarter ellipse shape for reflecting at least a part of outgoing light from the semiconductor light-emitting element;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector; and

a layer of the fluorescent substance provided on a reflective surface of the reflector, wherein the base substance is a substrate provided with a recessed portion, and at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion of the substrate so as not to emit light from the semiconductor light-emitting element directly to an outside of the semiconductor light-emitting device.

80. (New) A semiconductor light-emitting device, comprising:

a base substance;

a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and

a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits red light having an emission wavelength with its main emission peak in a wavelength range of 600 to 670 nm.

81. (New) The semiconductor light-emitting device according to claim 80, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$M_2 O_2 S$: Eu (M is any one or more elements selected from La, Gd and Y);
 $0.5 MgF_2 \cdot 3.5MgO \cdot GeO_2$: Mn;
 $Y_2 O_3$: Eu;
 $Y(P, V) O_4$: Eu; and
 YVO_4 : Eu.

82. (New) A semiconductor light-emitting device, comprising:
a base substance;
a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and
a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits green light having an emission wavelength with its main emission peak in a wavelength range of 500 to 540 nm.

83. (New) The semiconductor light-emitting device according to claim 82, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$RMg_2 Al_{1.6} O_{2.7}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);
 $RMgAl_{1.0} O_{1.7}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);
 ZnS : Cu;
 $SrAl_2 O_4$: Eu;
 $SrAl_2 O_4$: Eu, Dy;
 ZnO : Zn;
 $Zn_2 Ge_2 O_4$: Mn;

$Zn_2 SiO_4 : Mn$; and

$Q_3 MgSi_2 O_8 : Eu, Mn$ (Q is any one or more elements selected from Sr, Ba and Ca).

84. (New) A semiconductor light-emitting device, comprising:
- a base substance;
- a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and
- a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits blue light having an emission wavelength with its main emission peak in a wavelength range of 410 to 480 nm.

85. (New) The semiconductor light-emitting device according to claim 84, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$A_{1-0} (PO_4)_6 Cl_2 : Eu$ (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$XMg_2 Al_{1-6} O_{2-7} : Eu$ (X is any one or both elements selected from Sr and Ba);

$XMgAl_{1-0} O_{1-7} : Eu$ (X is any one or both elements selected from Sr and Ba);

$ZnS : Ag$;

$Sr_{1-0} (PO_4)_6 Cl_2 : Eu$;

$Ca_{1-0} (PO_4)_6 F_2 : Sb$;

$Z_3 MgSi_2 O_8 : Eu$ (Z is any one or more elements selected from Sr, Ca and Ba);

$SrMgSi_2 O_8 : Eu$;

$Sr_2 P_2 O_7 : Eu$; and

$CaAl_2 O_4 : Eu, Nd$.

86. (New) A semiconductor light-emitting device, comprising:

a base substance;

a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and

a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits blue green light having an emission wavelength with its main emission peak in a wavelength range of 480 to 500 nm.

87. (New) The semiconductor light-emitting device according to claim 86, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{Sr}_4 \text{Al}_{14} \text{O}_{25}$: Eu;

$\text{Sr}_4 \text{Al}_{14} \text{O}_{25}$: Eu, Dy;

$\text{L}_1 \text{O}(\text{PO}_4)_6 \text{Cl}_2$: Eu (L is any one or more elements selected from Ba, Ca and Mg);

and

$\text{Sr}_2 \text{Si}_3 \text{O}_8 \cdot 2\text{SrCl}_2$: Eu.

88. (New) A semiconductor light-emitting device, comprising:

a base substance;

a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and

a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits orange light having an emission wavelength with its main emission peak in a wavelength range of 570 to 600 nm.

89. (New) The semiconductor light-emitting device according to Claim 88, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

ZnS: Mn; and

ZnS: Cu, Mn, Co.

90. (New) The semiconductor light-emitting device according to Claim 89, wherein a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.

91. (New) The semiconductor light-emitting device according to Claim 82, wherein a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.

92. (New) The semiconductor light-emitting device according to Claim 84, wherein a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.

93. (New) The semiconductor light-emitting device according to Claim 86, wherein a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.

94. (New) The semiconductor light-emitting device according to Claim 88, wherein a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin includes the fluorescent substance.

95. (New) The semiconductor light-emitting device according to Claim 90, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
and

at least a part of the two lead frames and the semiconductor light-emitting element
are sealed with the sealing resin.

96. (New) The semiconductor light-emitting device according to Claim 90, wherein
the base substance is an insulator connected to ends of a pair of lead frames;
the semiconductor light-emitting element is connected to metallic wiring formed on
the insulator; and

at least a part of the pair of lead frames, the insulator and the semiconductor light-
emitting element are sealed with the sealing resin.

97. (New) The semiconductor light-emitting device according to Claim 80, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
the fluorescent substance is filled in the cup-shaped mount section; and
at least a part of the two lead frames, the semiconductor light-emitting element and
the fluorescent substance are sealed with a sealing resin.

98. (New) The semiconductor light-emitting device according to Claim 82, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;

the fluorescent substance is filled in the cup-shaped mount section; and
at least a part of the two lead frames, the semiconductor light-emitting element and
the fluorescent substance are sealed with a sealing resin.

99. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
the fluorescent substance is filled in the cup-shaped mount section; and
at least a part of the two lead frames, the semiconductor light-emitting element and
the fluorescent substance are sealed with a sealing resin.
100. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
the fluorescent substance is filled in the cup-shaped mount section; and
at least a part of the two lead frames, the semiconductor light-emitting element and
the fluorescent substance are sealed with a sealing resin.
101. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
the fluorescent substance is filled in the cup-shaped mount section; and
at least a part of the two lead frames, the semiconductor light-emitting element and
the fluorescent substance are sealed with a sealing resin.
102. (New) The semiconductor light-emitting device according to Claim 80, wherein

the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
a coating member is filled in the cup-shaped mount section and the fluorescent
substance is disposed on the coating member; and
at least a part of the two lead frames, the semiconductor light-emitting element, the
coating member and the fluorescent substance are sealed with a sealing resin.

103. (New) The semiconductor light-emitting device according to Claim 82, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
a coating member is filled in the cup-shaped mount section and the fluorescent
substance is disposed on the coating member; and
at least a part of the two lead frames, the semiconductor light-emitting element, the
coating member and the fluorescent substance are sealed with a sealing resin.

104. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped
mount section of the lead frame and electrically connected to another lead frame by wire bonding;
a coating member is filled in the cup-shaped mount section and the fluorescent
substance is disposed on the coating member; and
at least a part of the two lead frames, the semiconductor light-emitting element, the
coating member and the fluorescent substance are sealed with a sealing resin.

105. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;

a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

106. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a lead frame having a cup-shaped mount section;
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;
a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and
at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

107. (New) The semiconductor light-emitting device according to Claim 80, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;
a sealing resin for sealing the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.

108. (New) The semiconductor light-emitting device according to Claim 82, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected the metallic wiring on the substrate;
a sealing resin for sealing the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.

109. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected the metallic wiring
on the substrate;
a sealing resin for sealing the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.
110. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected the metallic wiring
on the substrate;
a sealing resin for sealing the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.
111. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected the metallic wiring
on the substrate;
a sealing resin for sealing the semiconductor light-emitting element is included; and
the sealing resin includes the fluorescent substance.
112. (New) The semiconductor light-emitting device according to Claim 80, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate and disposed in a recessed portion; and
the fluorescent substance is filled in the recessed portion.
113. (New) The semiconductor light-emitting device according to Claim 82, wherein

- the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and
the fluorescent substance is filled in the recessed portion.
114. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and
the fluorescent substance is filled in the recessed portion.
115. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and
the fluorescent substance is filled in the recessed portion.
116. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion; and
the fluorescent substance is filled in the recessed portion.
117. (New) The semiconductor light-emitting device according to Claim 112, wherein
the recessed portion is formed by a frame disposed on the substrate.
118. (New) The semiconductor light-emitting device according to Claim 80, wherein
the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;
a sealing resin is filled in the recessed portion; and
the fluorescent substance is disposed on the sealing resin.

119. (New) The semiconductor light-emitting device according to Claim 82, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;
a sealing resin is filled in the recessed portion; and
the fluorescent substance is disposed on the sealing resin.
120. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;
a sealing resin is filled in the recessed portion; and
the fluorescent substance is disposed on the sealing resin.
121. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;
a sealing resin is filled in the recessed portion; and
the fluorescent substance is disposed on the sealing resin.
122. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate and disposed in a recessed portion;
a sealing resin is filled in the recessed portion; and
the fluorescent substance is disposed on the sealing resin.

123. (New) The semiconductor light-emitting device according to Claim 80, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;
a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;
a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and
the fluorescent substance is included in the sealing resin.
124. (New) The semiconductor light-emitting device according to Claim 82, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;
a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;
a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and
the fluorescent substance is included in the sealing resin.
125. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is included in the sealing resin.

126. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting
reflected light from the reflector is included; and

the fluorescent substance is included in the sealing resin.

127. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting
reflected light from the reflector is included; and

the fluorescent substance is included in the sealing resin.

128. (New) The semiconductor light-emitting device according to Claim 80, wherein
the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

129. (New) The semiconductor light-emitting device according to Claim 82, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting
reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that
reflects light.

130. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

131. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

132. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

133. (New) The semiconductor light-emitting device according to Claim 80, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is
disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting
reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that
reflects light.

134. (New) The semiconductor light-emitting device according to Claim 82, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is
disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

135. (New) The semiconductor light-emitting device according to Claim 84, wherein the base substance is a substrate provided with metallic wiring; the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

136. (New) The semiconductor light-emitting device according to Claim 86, wherein the base substance is a substrate provided with metallic wiring; the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

137. (New) The semiconductor light-emitting device according to Claim 88, wherein the base substance is a substrate provided with metallic wiring; the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

138. (New) The semiconductor light-emitting device according to Claim 80, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

139. (New) The semiconductor light-emitting device according to Claim 82, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

140. (New) The semiconductor light-emitting device according to Claim 84, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting
reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that
reflects light.

141. (New) The semiconductor light-emitting device according to Claim 86, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting
reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

142. (New) The semiconductor light-emitting device according to Claim 88, wherein
the base substance is a substrate provided with metallic wiring;
the semiconductor light-emitting element is electrically connected to the metallic
wiring on the substrate;
a reflector for reflecting at least a part of outgoing light from the semiconductor
light-emitting element is included;
a sealing resin for sealing the semiconductor light-emitting element and transmitting
reflected light from the reflector is included; and
a layer of the fluorescent substance is formed on a surface of the sealing resin that
reflects light.

143. (New) A semiconductor light-emitting device, comprising:
a base substance;
a semiconductor light-emitting element on the base substance, wherein the
semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420
nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes;
a first fluorescent substance;;
a second fluorescent substance; and
a third fluorescent substance, wherein
the first fluorescent substance has red outgoing light having emission wavelengths
with its main emission peak in a wavelength range of 600 to 670 nm;
the second fluorescent substance has green outgoing light having emission
wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;
the third fluorescent substance has blue outgoing light having emission wavelengths
with its main emission peak in a wavelength range of 410 to 480 nm; and

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color.

144. (New) The semiconductor light-emitting device according to claim 143, wherein the first fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$M_2 O_2 S$: Eu (M is any one or more elements selected from La, Gd and Y);

$0.5MgF_2 \cdot 3.5MgO \cdot GeO_2$: Mn;

$Y_2 O_3$: Eu,

$Y(P, V) O_4$: Eu; and

YVO_4 : Eu;

the second fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$RMg_2 Al_{16} O_{27}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);

$RMgAl_{10} O_{17}$: Eu, Mn (R is any one or both elements selected from Sr and Ba);

ZnS : Cu;

$SrAl_2 O_4$: Eu;

$SrAl_2 O_4$: Eu, Dy;

ZnO : Zn;

$Zn_2 Ge_2 O_4$: Mn;

$Zn_2 SiO_4$: Mn; and

$Q_3 MgSi_2 O_8$: Eu, Mn (Q is any one or more elements selected from Sr, Ba and Ca);

and

the third fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$A_{10}(PO_4)_6 Cl_2$: Eu (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$XMg_2 Al_{16} O_{27}$: E (X is any one or both elements selected from Sr and Ba);

$XMgAl_{10} O_{17}$: Eu (X is any one or both elements selected from Sr and Ba);

ZnS: Ag;
Sr_{1.0}(PO₄)₆Cl₂: Eu;
Ca_{1.0}(PO₄)₆F₂: Sb;
Z₃MgSi₂O₈: Eu (Z is any one or more elements selected from Sr, Ca and Ba);
SrMgSi₂O₈: Eu;
Sr₂P₂O₇: Eu; and
CaAl₂O₄: Eu, Nd.

145. (New) The semiconductor light-emitting device according to Claim 143, wherein, assuming the total amount as 100 weight %,

the first fluorescent substance is between 50 weight % and 70 weight % inclusive;

the second fluorescent substance is between 7 weight % and 20 weight % inclusive;

and

the third fluorescent substance is between 20 weight % and 30 weight % inclusive.

146. (New) The semiconductor light-emitting device according to Claim 145, wherein

the sealing resin includes the first, second and third fluorescent substances; and

the proportion of the total weight of the first, second and third fluorescent substances to the weight of the sealing resin is between 0.5 and 1 inclusive.

147. (New) A light-emitting display device comprising;

a light source using the semiconductor light-emitting device according to Claim 64;

a light guiding plate for guiding light from the light source; and

red, green and blue color filters for transmitting light from the light guiding plate and dividing the light; the light-emitting display device, wherein

outgoing light from the semiconductor light-emitting device has a wavelength distribution that matches spectral characteristics of the color filters.

148. (New) The light-emitting display device according to Claim 147, wherein at least one of the following is adjusted so that the wavelength distribution of the outgoing light from the semiconductor light-emitting device matches spectral characteristics of the color filters:

the emission wavelength of the semiconductor light-emitting element;
the emission wavelength of the first fluorescent substance;
the emission wavelength of the second fluorescent substance;
the emission wavelength of the third fluorescent substance;
the mixture proportions of the first, second and third fluorescent substances; and
the proportion of the total weight of the first, second and third fluorescent substances to the weight of the sealing resin.

149.(New) The light-emitting display device according to Claim 147, wherein the light-emitting display device is a liquid crystal display device.

150. (New) The light-emitting display device according to Claim 148, wherein the light-emitting display device is a liquid crystal display device.

151. (New) The light-emitting display device according to Claim 80, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

152. (New) The light-emitting display device according to Claim 82, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

153. (New) The light-emitting display device according to Claim 84, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

154. (New) The light-emitting display device according to Claim 86, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

155. (New) The light-emitting display device according to Claim 88, wherein
the emission wavelength of the outgoing light is 400 to 420 nm.

156. (New) The light-emitting display device according to Claim 143, wherein
the emission wavelength of the outgoing light is 400 to 420 nm.